Product Qualification Report

IPAN60R210PFD7S

CoolMOS™

Description

This product qualification report describes the characteristics of the product with respect to quality and reliability.

The qualification sample selection was done on production lots which were manufactured and tested on standard production processes and meet the defined requirements.

The qualification test results of those products as outlined in this document are based on **JEDEC** for target applications and may reference existing qualification results of similar products. Such referencing is justified by the structural similarity of the products.

Qualification Assessment

Qualified according to **JEDEC Standard** and assessed as PASS

For further information about comparable products, please contact the nearest Infineon Technologies office (www.infineon.com).

IPAN60R210PFD7S **qualified since 2019**
PG-TO220-3
MSL: not applicable;

Electrical Stress Test Results:

Test Description	Abbr.	Condition	Duration	Lots/SS	Fail/Qty	Result
Parametric Verification	PV	-55°C, +25°C, +150°C		4 x 30	0 / 120	PASS
High Temperature Reverse Bias JESD22 A108	HTRB*	Ta ≥ 150°C V_{DS} ≥ 480V	500 h	4 x 77	0 / 308	PASS
High Temperature Gate Bias JESD22 A108	HTGB*	Ta = 150°C V_{GS} = +/-20V	500h	4 x 77	0 / 308	PASS
High Humidity High Temp. Reverse Bias JESD22 A101	H3TRB*	Ta = 85°C rh = 85% V_{DS} = 80V	500h	4 x 77	0 / 308	PASS
Intermitted Operational Life Test MIL-STD 750 / Meth.1037	IOL*	Delta T =100K	7500 cyc	4 x 77	0 / 308	PASS
ESD (HBM) JESD22-A114	HBM	Class 1C (1000 V to < 2000 V)				PASS
ESD (CDM) JESD22-C101	CDM	Class C3 (> 1000 V)				PASS

Environmental Stress Test Results:

Test Description	Abbr.	Condition	Duration	Lots/SS	Fail/Qty	Result
Pre-conditioning J-STD020 / JESD22 A113	PC	MSL and 3 x reflow		2 x 462	0 / 924	PASS
Temperature Cycling JESD22 A104	TC*	-55°C to +150°C	500 cyc	4 x 77	0 / 308	PASS
Unbiased Highly Accelerated Stress Test JESD22 A118	UHAST*	Ta = 130°C rh = 85%	96 h	4 x 77	0 / 308	PASS

Notes:
* For SMD devices reliability stress tests performed after preconditioning test (PC) according to JESD22

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Published by

Infineon Technologies AG

81726 München, Germany

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Document reference

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